NOTES:

A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. QFN (Quad Flatpack No-Lead) staggered multi-row package configuration.

⚠️ Pin A1 identifiers are located on both top and bottom of the package and within the zone indicated.
The Pin A1 identifiers are either a molded, marked, or metal feature.

⚠️ The package thermal pad must be soldered to the board for thermal and mechanical performance.
See the Product Data Sheet for details regarding the exposed thermal pad dimensions.
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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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